So What About Variability...

Sani R. Nassif

IBM Research – Austin

nassif@us.ibm.com

A Looming Problem

- Integrated circuit manufacturing variability has been increasing with process scaling.
- Within-die variability causes a decrease in circuit performance that is not recoverable by binning.
- Lack of models and analysis tools causes excessive conservatism in the design process and therefore reduces potential performance.

Variability Sources

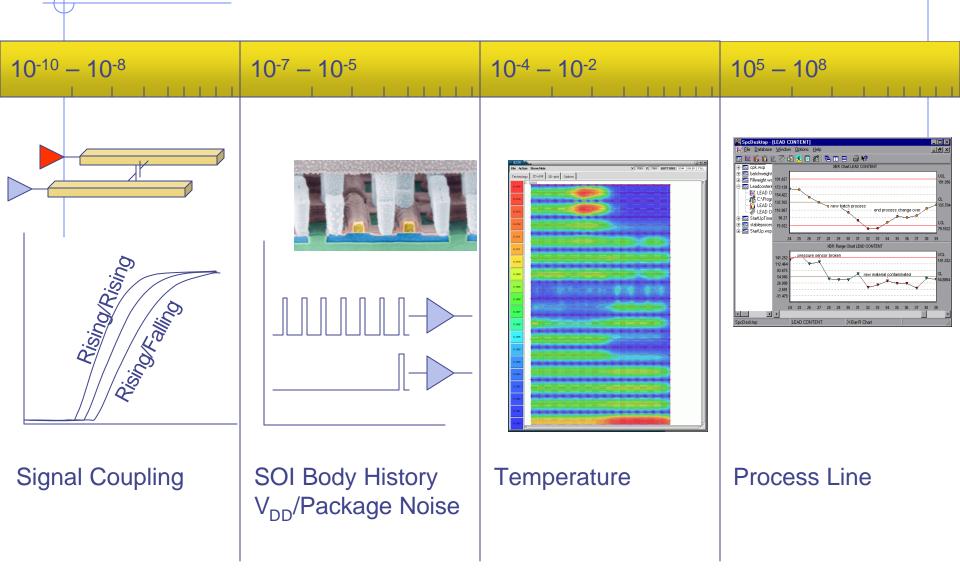
Physical:

- Changes in characteristics of devices and wires.
- Caused by IC manufacturing process & wear-out.
- Time scale: 108sec (months).

Environmental:

- Changes in V_{DD}, Temperature, local coupling.
- Caused by the specifics of the design implementation.
- ◆ Time scale: 10⁻⁶ to 10⁻¹⁰sec (clock tick).
- Roughly equal... Delay can change as much as 2X.

Variability Time Scales

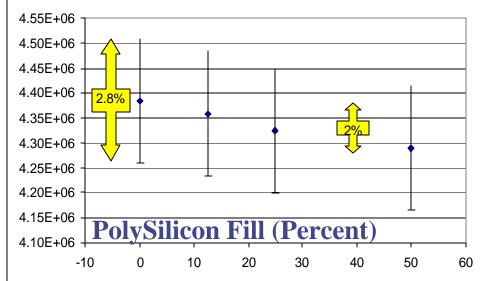


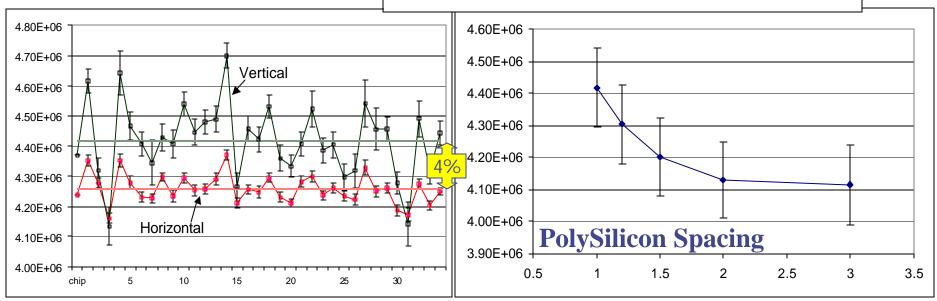
Modeling of Variability

Pre-PD vs. Post-PD are very different.

- Example: floor-plan location and power estimates can provide precise V_{DD} and T allowing potential correction.
- Pre-PD can only dealt with using worst-case analysis!

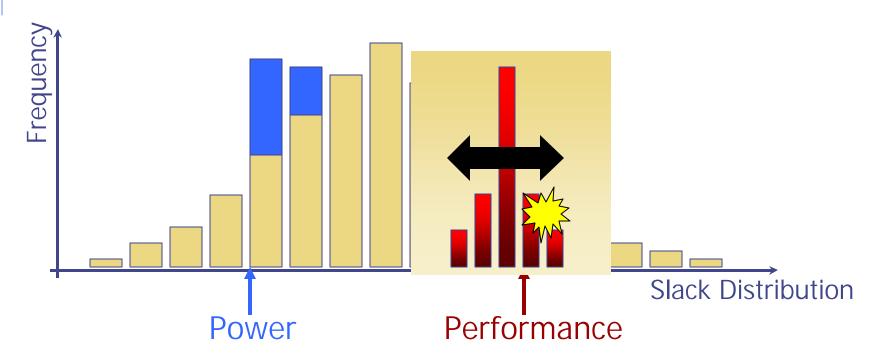
Magnitude... Systematic Effects





Design Factors

- Power and leakage constraints are driving designers to decrease overall path delay variability.
- This decrease results in more susceptibility to variability-induced timing fluctuations.



Specific Questions/Answers

- Where should timing robustness be stressed?
 - At the technology mapping level and below.
- Is variability really a problem?
 - Duh...
- How much tolerance is needed?
 - **30%**
- How well do current techniques do?
 - OK for die-to-die, badly for within-die.
- What phenomena do we need to consider?
 - Physical and Environmental impact on delay.